



Printed Circuit Boards
Interconnection Carriers

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

06 150 FR4 35 L20.18 P18_10_06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_150_FR4_35_L20.18_p18_10_06

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		A1			
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)		
	100 μ	Prepreg			(100 μ PrePreg-Type: 2116)		
Layer-2	18 μ	Copper			B		
	200 μ	L-FR4					
Layer-3	18 μ	Copper					A2
	180 μ	Prepreg				(180 μ PrePreg-Type: 7628)	
	180 μ	Prepreg					
	180 μ	Prepreg					
Layer-4	100 μ	Prepreg				A2	
	18 μ	Copper					
	200 μ	L-FR4					
Layer-5	18 μ	Copper					
	100 μ	Prepreg					
	60 μ	Prepreg					
Layer-99	35 μ	Copper					A2